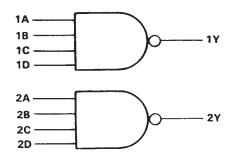
- Package Options Include Ceramic Chip Carriers and Flat Packages in Addition to Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

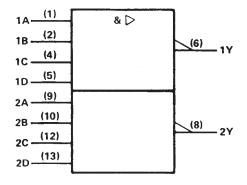
These devices contain two independent 4-input positive-NAND 50-ohm line drivers. They perform the Boolean function $Y = \overline{ABCD}$.

The SN54S140 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74S140 is characterized for operation from 0°C to 70°C.

logic diagram (each driver)



logic symbol†



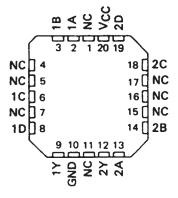
[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN54S140 . . . J OR W PACKAGE SN74S140 . . . D OR N PACKAGE (TOP VIEW)

1A[]	U14 VCC
1B ☐ 2	13 2D
NC □3	12] 2C
1C ☐ 4	11DNC
1D[5	10 2B
17□6	9 2A
GND 7	8 2Y

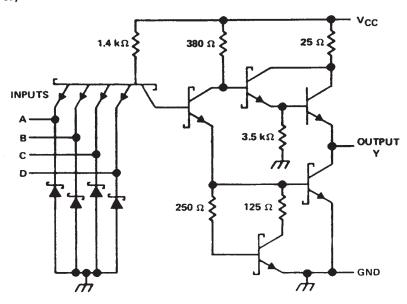
SN54S140 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection

SDLS210 - DECEMBER 1983 - REVISED MARCH 1988

schematic (each driver)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage	
Operating free-air temperature range: SN54'	– 55°C to 125°C
SN74'	
Storage temperature range	– 65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

			SN54S140			SN74S140		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC} Supply voltage	1100	4.5	5	5.5	4.75	5	5.25	V
VIH High-level input voltage		2			2			V
VIL Low-level input voltage				0,8			0.8	V
IOH High-level output current				- 40			- 40	mA
IOL Low-level output current				60			60	mA
TA Operating free-air temperatur		- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONST			SN54S140				SN74S140		
		1521 CONDIT	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT		
VIK	V _{CC} = MIN,	I _I = - 18 mA	· · · · · · · · · · · · · · · · · · ·			- 1.2			- 1.2	V	
\/-··	V _{CC} = MIN,	V _{IL} = 0.8 V,	I _{OH} = - 3 mA	2.5	3.4		2.7	3.4		V	
VOH	V _{CC} = MIN,	VIL = 0.5 V,	$R_O = 50 \Omega$ to GND	2			2)	
VOL	V _{CC} = MIN,	V _{1H} = 2 V,	I _{OL} = 60 mA			0.5			0.5	V	
lį	V _{CC} = MAX,	V _I = 5.5 V				1			1	mA	
ЧН	V _{CC} = MAX,	V _{IH} = 2.7 V				0.1			0.1	mA	
Iις	V _{CC} = MAX,	V _{IL} = 0.5 V				- 4			- 4	mA	
los §	V _{CC} = MAX			- 50		- 225	- 50		- 225	mA	
1ссн	V _{CC} = MAX,	V ₁ = 0 V			10	18		10	18	mA	
ICCL.	V _{CC} = MAX,	V ₁ = 4.5 V			25	44		25	44	mA	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	IDITIONS	MIN TYP	MAX	UNIT
tPLH			D -03 O	C = 50 = 5	4	6.5	ns
t _{PHL}	Anv	V	R _L = 93 Ω,	$C_L = 50 pF$	4	6.5	ns
tPLH	Any	1	B. = 02 O	C. = 150 pE	6		ns
tPHL_			R _L = 93 Ω,	C _L = 150 pF	6		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed 100 milliseconds.







PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/08101BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/08101BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/08101BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN54S140J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54S140J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74S140D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S140N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S140N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S140N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S140NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S140NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S140NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140NSRE4	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S140NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54S140FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S140FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S140J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S140J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S140W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S140W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.



PACKAGE OPTION ADDENDUM

26-Sep-2005

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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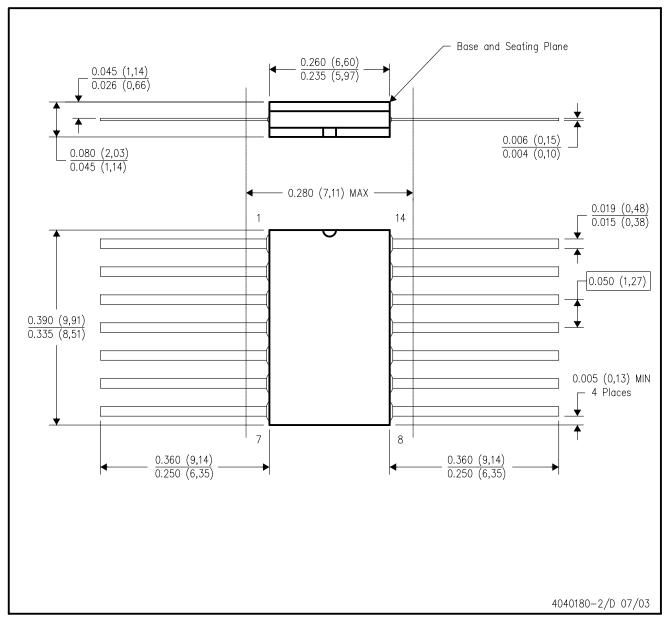
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

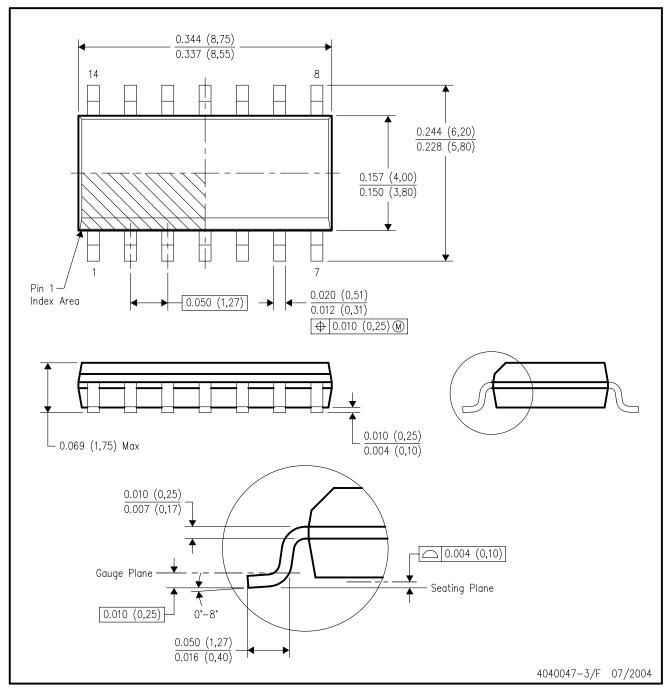


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

